

#### N-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	Ι <sub>D</sub> Τ <sub>A</sub> = +25°C
20V	0.4Ω @ V <sub>GS</sub> = 4.5V	1A
	0.7Ω @ V <sub>GS</sub> = 1.8V	0.8A

### **Features and Benefits**

- Low On-Resistance
- Very Low Gate Threshold Voltage V<sub>GS(TH)</sub>, 1.0V Max.
- Low Input Capacitance
- Fast Switching Speed
- Ultra-Small Surfaced Mount Package
- Ultra-Low Package Profile, 0.4mm Maximum Package Height
- **ESD Protected Gate**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

## **Description and Applications**

This new generation MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- DC-DC Converters
- **Power Management Functions**

#### **Mechanical Data**

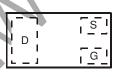
- Case: X2-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu over Copper Leadframe; Solderable per MIL-STD-202, Method 208@4)
- Weight: 0.001 grams (Approximate)



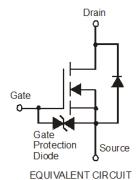




**Bottom View** 



Top View Internal Schematic



#### Ordering Information (Note 4)

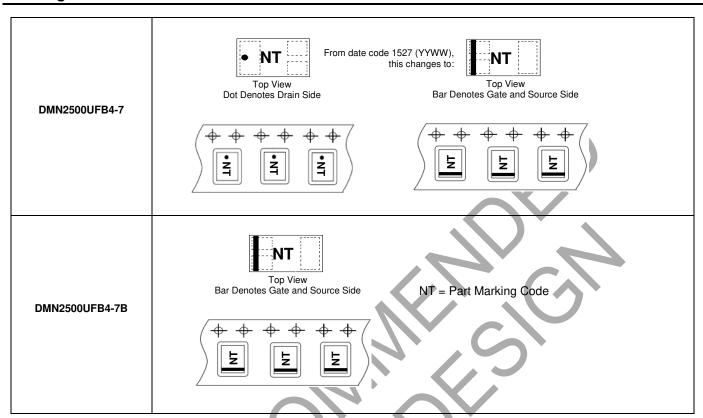
Part Number	Case	Packaging		
DMN2500UFB4-7	X2-DFN1006-3	3,000/Tape & Reel		
DMN2500UFB4-7B	X2-DFN1006-3	10,000/Tape & Reel		
Notes: 1. No purposely added lead, Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.				

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- 2 See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



## **Marking Information**





#### NOT RECOMMENDED FOR NEW DESIGN USE DMN2450UFB4

**DMN2500UFB4** 

## **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	$V_{DSS}$	20	V		
Gate-Source Voltage	$V_{GSS}$	±6	V		
Continuous Dusin Comment (Notes EVV 4 EV	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I <sub>D</sub>	810 640	mA
Continuous Drain Current (Note 5) V <sub>GS</sub> = 4.5V	t<10s	$T_A = +25$ °C $T_A = +70$ °C	I <sub>D</sub>	950 750	mA
Continuous Dusin Comment (Notes C) V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	1000 800	mA
Continuous Drain Current (Note 6) V <sub>GS</sub> = 4.5V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	1200 1000	mA
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	4	Α		
Maximum Body Diode Continuous Current	Is	850	mA		

## Thermal Characteristics (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	P <sub>D</sub>	0.46 0.29	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State		279	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	210	°C/W
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	Pp	0.95	- W
Total Fower Dissipation (Note o)	$T_A = +70^{\circ}C$	P	0.6	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	9	134	°C/W
Thermal resistance, suriction to Ambient (Note 6)	t<10s	$R_{ heta JA}$	100	°C/W
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	ı	-	٧	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>		1	100	nA	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	-	-	±1.0	μΑ	$V_{GS} = \pm 4.5V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.5	1	1.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
			0.3	0.4		$V_{GS} = 4.5V, I_D = 600mA$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	-	0.4	0.5	Ω	$V_{GS} = 2.5V, I_D = 500mA$	
			0.5	0.7		$V_{GS} = 1.8V, I_D = 350mA$	
Forward Transfer Admittance	Y <sub>fs</sub>	-	1.4	-	S	$V_{DS} = 10V, I_D = 400mA$	
Diode Forward Voltage	V <sub>SD</sub>	-	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 150mA$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	-	60.67	-	pF	V <sub>DS</sub> =16V, V <sub>GS</sub> = 0V, f = 1.0MHz	
Output Capacitance	Coss	-	9.68	-	рF		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	5.37	-	pF	1 = 1.0WHZ	
Gate Resistance	Rg	-	93	-	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge	Qg	-	736.6	-	рC	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
Gate-Source Charge	Q <sub>gs</sub>	-	93.6	-	рC	$V_{GS} = 4.5V, V_{DS} = 10V,$ $I_{D} = 250mA$	
Gate-Drain Charge	$Q_{gd}$	-	116.6	-	рC		
Turn-On Delay Time	t <sub>D(ON)</sub>	-	5.1	-	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$ $R_{L} = 47\Omega, R_{G} = 10\Omega,$ $I_{D} = 200\text{mA}$	
Turn-On Rise Time	t <sub>R</sub>	-	7.4	-	ns		
Turn-Off Delay Time	t <sub>D(OFF)</sub>	-	26.7	-	ns		
Turn-Off Fall Time	t <sub>F</sub>	-	12.3	-	ns		

 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate. Notes:

7. Short duration pulse test used to minimize self-heating effect.

8. Guaranteed by design. Not subject to product testing.

2.5

1.2

1.5

3



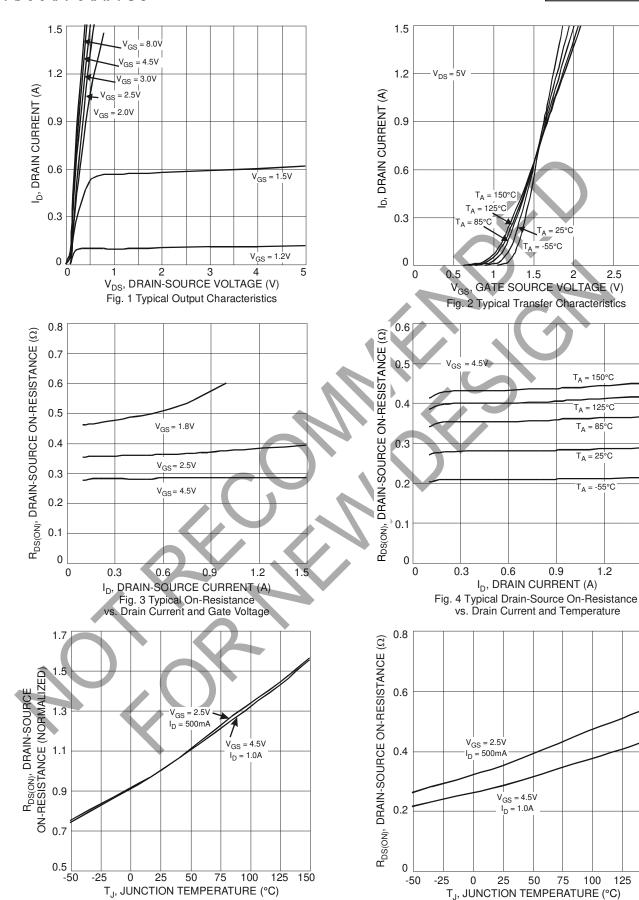


Fig. 5 On-Resistance Variation with Temperature

125 150

Fig. 6 On-Resistance Variation with Temperature



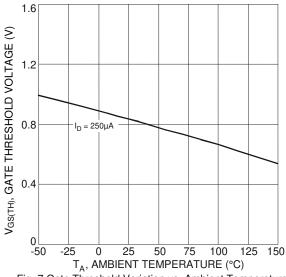
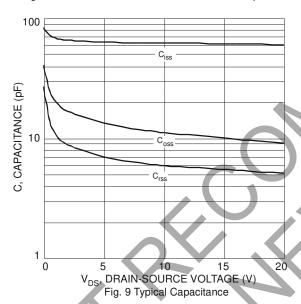
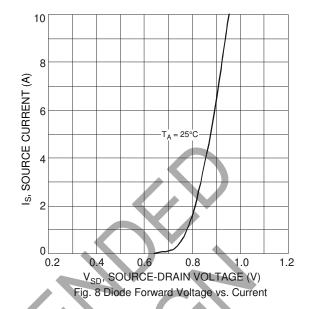
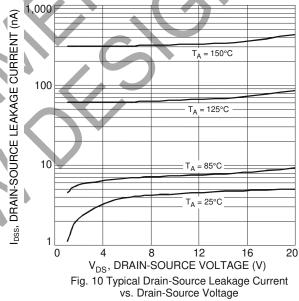


Fig. 7 Gate Threshold Variation vs. Ambient Temperature





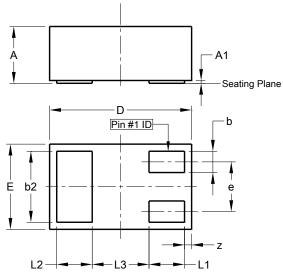




## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN1006-3

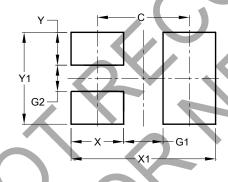


X2-DFN1006-3					
Dim	Min	Max	Тур		
Α	_	0.40	_		
A1	0.00	0.05	0.03		
b	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.05	1.00		
Е	0.55	0.65	0.60		
е	-	-	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3			0.40		
Z	0.02	0.08	0.05		
All Dimensions in mm					

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN1006-3



Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Υ	0.25
Y1	0.70



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**DMN2500UFB4** 

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